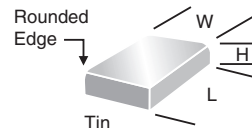
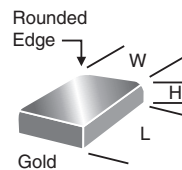


TopLine®



GOLD & TIN SOLDERABLE CHIPS FULLY CONDUCTIVE



DUMMY COMPONENT ORDERING INFORMATION

CHIP SIZE		TAPE MAT'L	TAPING INFO		7" (180mm) Tape & Reel Part Number	QTY
INCH	METRIC		WIDTH	PITCH		
GOLD CHIPS						
0201	0603	Paper	8mm	2mm	SS0201P7A-GOLD	15,000
0402	1005	Paper	8mm	2mm	SS0402P7A-GOLD	10,000
0603	1608	Paper	8mm	4mm	SS0603P7A-GOLD	4,000
0805	2012	Plastic	8mm	4mm	SS0805E7A-GOLD	4,000
1206	3216	Paper	8mm	4mm	SS1206P7A-GOLD	4,000
Tin CHIPS						
0201	0603	Paper	8mm	2mm	SS0201P7A-TIN	15,000
0402	1005	Paper	8mm	2mm	SS0402P7A-TIN	10,000
0603	1608	Paper	8mm	4mm	SS0603P7A-TIN	4,000
0805	2012	Plastic	8mm	4mm	SS0805E7A-TIN	4,000
1206	3216	Paper	8mm	4mm	SS1206P7A-TIN	4,000

INCH DIMENSIONS:

Inch Code	L	W	H	Tol
0201	0.023	0.012	0.012	+/- 0.002
0402	0.040	0.020	0.020	+/- 0.003
0603	0.062	0.035	0.035	+/- 0.003
0805	0.075	0.052	0.037	+/- 0.003
1206	0.120	0.060	0.048	+/- 0.003

METRIC DIMENSIONS:

Metric Code	L	W	H	Tol
0603	0.50	0.30	0.30	+/- 0.050
1005	1.00	0.50	0.50	+/- 0.076
1608	1.50	0.90	0.90	+/- 0.076
2012	1.91	1.32	0.94	+/- 0.076
3216	3.02	1.52	1.22	+/- 0.076

**I
N
F
O** Fully conductive chips available in 2 plating materials: Gold (Au) and Tin (Sn).
Smooth, rounded edges for soldering.
Ceramic substrate fully metalized plating on all sides. Fully solderable using standard reflow.
Use for a variety of applications requiring zero ohm conductivity on all sides. Lead Free. RoHS compliant.



SS Series and Submount Questionnaire

Email: sales@topline.tv
Tel 1-800-776-9888
Fax 1-478-451-3000

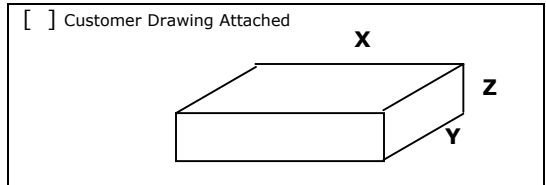
Contact:

Name: _____
 Company: _____
 Email: _____
 Project Ref: _____

Title: _____
 Dept: _____
 Tel: _____ Ext _____

Outline Size: [] mm [] μ m [] mil [] inch

Body Size: X= Y= Z=
 Tolerance: X= Y= Z=



Core Material:

[] Ceramic/Alumina [] FR4 [] Si [] Plastic
 [] Other:

Plating:

[] Ni-Au Solderable [] Ni-Au Wire-Bondable
 Min Au _____ [] μ m [] micro-inch
 Max Au _____ [] μ m [] micro-inch
 Min Ni _____ [] μ m [] micro-inch
 Max Ni _____ [] μ m [] micro-inch
 [] Sn [] Sn/Pb [] Cu [] Ag
 [] Other: _____ [] RoHS

Metallization Surfaces:

[] 6-sides [] 4-sides [] 1-Side

Application:

[] Conductive Test Point or Contact Point
 [] Submount (Mount into cavity for wirebonding or jumper)
 [] Substrate (Other components mount on side)
 [] Pedestal (Holds up other components)
 [] Other:

Packaging:

[] Tape and Reel
 [] Tray
 [] Any
 [] Other _____

Temperature Requirement:

Operating Temperature Range: Min _____ $^{\circ}$ C ~ Max _____ $^{\circ}$ C
 Soldering Temperature Range: Min _____ $^{\circ}$ C ~ Max _____ $^{\circ}$ C
 Storage Temperature Range: Min _____ $^{\circ}$ C ~ Max _____ $^{\circ}$ C

Operating Environment:

Frequency: From _____ to _____
 Vibration Requirement: _____
 Hermeticity/Water Absorption: _____